

## TUTORIAL 8 PN Junction under an External Voltage Bias

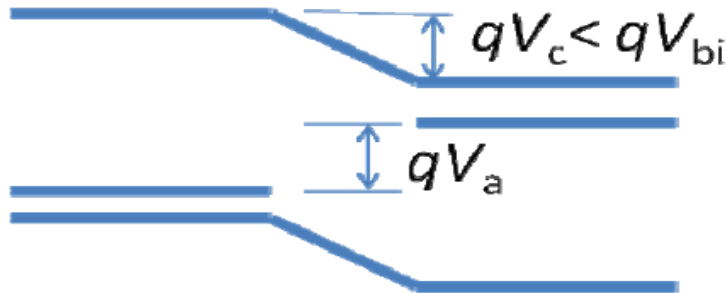
1. An abrupt Si pn junction is doped uniformly with  $1 \times 10^{16} \text{ cm}^{-3}$  impurity on the n-side and  $1 \times 10^{17} \text{ cm}^{-3}$  impurity on the p-side. The cross-sectional area of the pn junction is  $1 \times 10^{-4} \text{ cm}^2$ . Calculate the following parameters under (i) a forward bias of 0.65 V and (ii) a reverse of 2 V. Draw the energy band diagram under both biasing conditions, indicating clearly the extent of the band bending.
- a. contact potential;
  - b. the total depletion width;
  - c. the depletion width in the n- and p-side;
  - d. the space charge in each side of the depletion region;
  - e. peak electric field.

[0.104 V; 2.75 V; 0.122  $\mu\text{m}$ ; 0.628  $\mu\text{m}$ ; 0.111  $\mu\text{m}$ ; 0.011  $\mu\text{m}$ ;  $1.76 \times 10^{-12} \text{ C}$ ;  $-1.69 \times 10^4 \text{ V/cm}$ ; 0.571  $\mu\text{m}$ ; 0.057  $\mu\text{m}$ ;  $9.12 \times 10^{-12} \text{ C}$ ;  $-8.73 \times 10^4 \text{ V/cm}$ ]

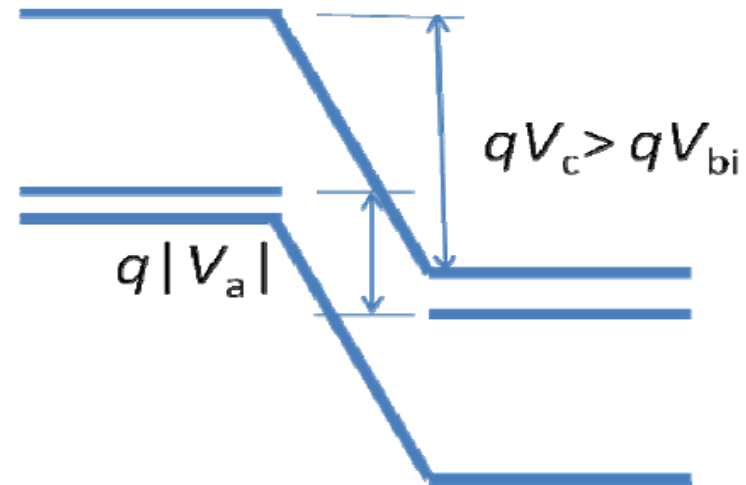
## a. contact potential

### Energy Band Diagrams

#### Forward Bias



#### Reverse Bias



Built-in potential:

$$V_{bi} = \frac{k_B T}{q} \ln \left( \frac{N_a N_d}{n_i^2} \right) = 0.0259 \ln \left[ \frac{1 \times 10^{17} \times 1 \times 10^{16}}{(1.5 \times 10^{10})^2} \right]$$
$$= 0.754 \text{ V}$$

Under forward bias,  $V_c = 0.754 - 0.65 = 0.104 \text{ V}$

Under reverse bias,  $V_c = 0.754 + 2 = 2.75 \text{ V}$

## b. the total depletion width

Under forward bias,

$$\begin{aligned}W_{\text{FB}} &= \left[ \frac{2\epsilon_r\epsilon_0}{q} (V_{\text{bi}} - V_a) \left( \frac{1}{N_a} + \frac{1}{N_d} \right) \right]^{1/2} \\&= \left[ \frac{2 \times 11.8 \times 8.85 \times 10^{-14} \times 0.104}{1.6 \times 10^{-19}} \left( \frac{1}{1 \times 10^{17}} + \frac{1}{1 \times 10^{16}} \right) \right]^{1/2} \\&= 1.22 \times 10^{-5} \text{ cm} \quad \text{or } 0.122 \text{ } \mu\text{m}\end{aligned}$$

Under reverse bias,

$$\begin{aligned}W_{\text{RB}} &= \left[ \frac{2\epsilon_r\epsilon_0}{q} (V_{\text{bi}} + |V_a|) \left( \frac{1}{N_a} + \frac{1}{N_d} \right) \right]^{1/2} \\&= \left[ \frac{2 \times 11.8 \times 8.85 \times 10^{-14} \times 2.75}{1.6 \times 10^{-19}} \left( \frac{1}{1 \times 10^{17}} + \frac{1}{1 \times 10^{16}} \right) \right]^{1/2} \\&= 6.28 \times 10^{-5} \text{ cm} \quad \text{or } 0.628 \text{ } \mu\text{m}\end{aligned}$$

**c. Find  $x_n$  and  $x_p$**

Charge neutrality:  $x_p N_a = x_n N_d$  (1)

Geometrically,  $x_p + x_n = W$  (2)

From (1) and (2),

$$x_n = \left( \frac{N_a}{N_a + N_d} \right) W$$
$$x_p = \left( \frac{N_d}{N_a + N_d} \right) W$$

**d. Space charge:**  $Q_{sc} = q N_A x_p A = q N_D x_n A$

**e. Max. electric field:**  $\xi_{max} = -\frac{q N_A x_p}{\epsilon_r \epsilon_0} = -\frac{q N_D x_n}{\epsilon_r \epsilon_0}$

(negative sign means electric field is pointing in the negative x-direction)

Under forward bias,

$$\begin{aligned}x_n &= \left( \frac{1 \times 10^{17}}{1 \times 10^{17} + 1 \times 10^{16}} \right) \times 0.122 \\&= 0.111 \mu\text{m} \\x_p &= W - x_n = 0.011 \mu\text{m}\end{aligned}$$

Space charge on either side of the junction,

$$Q = qN_a x_p A = qN_d x_n A = 1.76 \times 10^{-12} \text{ C}$$

Peak electric field (at metallurgical junction),

$$\xi_m = -\frac{qN_a x_p}{\epsilon_r \epsilon_0} = -\frac{qN_d x_n}{\epsilon_r \epsilon_0} = -1.69 \times 10^4 \text{ V/cm}$$

Under reverse bias,

$$\begin{aligned}x_n &= \left( \frac{1 \times 10^{17}}{1 \times 10^{17} + 1 \times 10^{16}} \right) \times 0.628 \\&= 0.571 \mu\text{m} \\x_p &= W - x_n = 0.057 \mu\text{m}\end{aligned}$$

Space charge on either side of the junction,

$$Q = qN_a x_p A = qN_d x_n A = 9.12 \times 10^{-12} \text{ C}$$

Peak electric field (at metallurgical junction),

$$\xi_m = -\frac{qN_a x_p}{\epsilon_r \epsilon_0} = -\frac{qN_d x_n}{\epsilon_r \epsilon_0} = -8.73 \times 10^4 \text{ V/cm}$$

2. A silicon p-n junction diode has the following parameters at 300 K,  $D_n = 25 \text{ cm}^2/\text{sec}$ ,  $D_p = 10 \text{ cm}^2/\text{sec}$ ,  $\tau_n = \tau_p = 0.5 \text{ } \mu\text{s}$ ,  $\epsilon_r = 11.7$ ,  $n_i = 1.5 \times 10^{10} / \text{cm}^3$ . Given that the electron diffusion current density is  $20 \text{ A/cm}^2$  and the hole diffusion current density is  $5 \text{ A/cm}^2$  at a forward bias of  $0.65 \text{ V}$ , **determine the doping densities of the p- and the n-regions of the diode.**

$$(N_a = 10^{15} / \text{cm}^3 \text{ and } N_d = 2.5 \times 10^{15} / \text{cm}^3)$$

$$J_n(-x_p) = 20 \text{ A/cm}^2$$

$$J_p(x_n) = 5 \text{ A/cm}^2$$

## Determine $N_a$

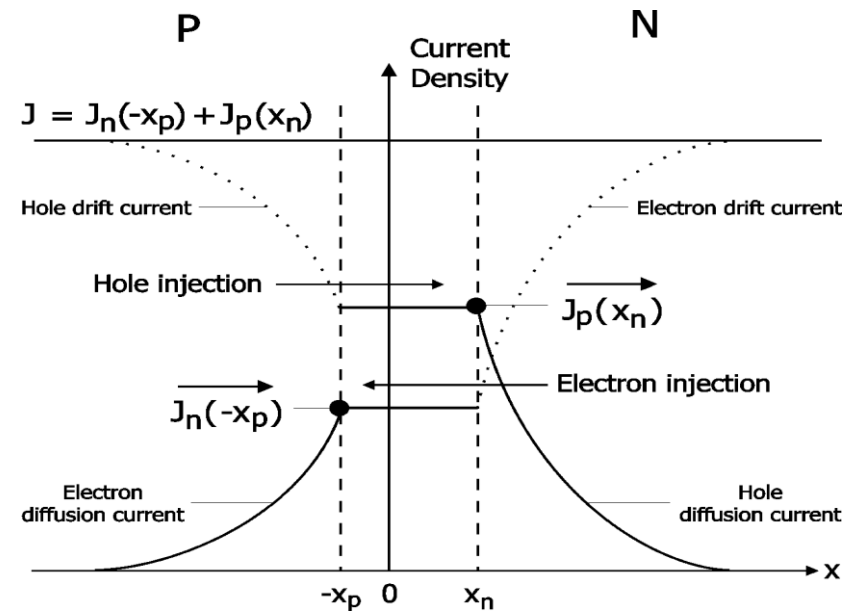
Use  $J_n$  to find  $N_a$  as  $J_n$  is the minority carrier current density in p-side

$$J_n(-x_p) = q \frac{D_n}{L_n} \Delta n_p(-x_p)$$

$$\begin{aligned} \therefore J_n &= q \frac{D_n}{L_n} n_{po} \left( \exp \frac{qV}{kT} - 1 \right); \\ &= q \sqrt{\frac{D_n}{\tau_n}} \frac{n_i^2}{N_a} \left( \exp \frac{qV}{kT} - 1 \right) \end{aligned} \quad (2)$$

$$20 = 1.6 \times 10^{-19} \sqrt{\frac{25}{5 \times 10^{-7}}} \frac{2.25 \times 10^{20}}{N_a} \left( \exp \frac{0.65}{0.026} - 1 \right)$$

$$\Rightarrow N_a = 1.0 \times 10^{15} \text{ cm}^{-3}$$





Determine  $N_d$

*Similarly,*

$$J_p = q \sqrt{\frac{D_p}{\tau_p}} \frac{n_i^2}{N_d} \left( \exp \frac{qV}{kT} - 1 \right)$$

$$5 = 1.6 \times 10^{-19} \sqrt{\frac{10}{5 \times 10^{-7}}} \frac{2.25 \times 10^{20}}{N_d} \left( \exp \frac{0.65}{0.026} - 1 \right)$$

$$\Rightarrow N_d = 2.55 \times 10^{15} \text{ cm}^{-3}$$

3. Show that the ratio of the hole and electron currents injected across an ideal pn junction is given by

$$\frac{J_p(x = x_n)}{J_n(x = -x_p)} = \frac{L_n \sigma_p}{L_p \sigma_n}$$

where  $\sigma_n$  and  $\sigma_p$  are the conductivities of the n and p regions, respectively; You may assume the base lengths to be much longer than the respective minority carrier diffusion lengths.

What is the implication if the **p**-region is doped much more heavily than the **n**-region?

Minority carrier (diffusion) current densities in a long-base pn junction:

$$J_p(x = x_n) = \frac{qD_p p_{no}}{L_p} \left[ e^{qV_a / (k_B T)} - 1 \right] \quad (\text{for holes}) \quad (1a)$$

$$J_n(x = -x_p) = \frac{qD_n n_{po}}{L_n} \left[ e^{qV_a / (k_B T)} - 1 \right] \quad (\text{for electrons}) \quad (1b)$$

$x_n$  and  $x_p$  are the space charge region widths on the n- and p-type sides.

Dividing (1a) by (1b),

$$\frac{J_p(x = x_n)}{J_n(x = -x_p)} = \left( \frac{D_p p_{no}}{L_p} \right) \left( \frac{L_n}{D_n n_{po}} \right) \quad (2)$$

Assuming complete ionization of dopants and noting that  $N_D, N_A$  are  $\gg n_i$ , in the n and p regions, respectively

$$p_{no} = \frac{n_i^2}{n_{no}} \approx \frac{n_i^2}{N_D} \quad \text{for the n region} \quad (3a)$$

$$n_{po} = \frac{n_i^2}{p_{po}} \approx \frac{n_i^2}{N_A} \quad \text{for the p region} \quad (3b)$$

Substituting (3a) and (3b) into (2),

$$\frac{J_p(x = x_n)}{J_n(x = -x_p)} = \frac{D_p L_n N_A}{D_n L_p N_D}$$

Recall that  $D_p = \mu_p k_B T / q$  and  $D_n = \mu_n k_B T / q$  (Einstein's relations),

$$\frac{J_p(x = x_n)}{J_n(x = -x_p)} = \frac{\mu_p L_n N_A}{\mu_n L_p N_D} = \frac{L_n (q \mu_p N_A)}{L_p (q \mu_n N_D)}$$

→  $\therefore \frac{J_p(x = x_n)}{J_n(x = -x_p)} = \frac{L_n \sigma_p}{L_p \sigma_n} \quad (4)$

If  $N_A \gg N_D$ ,  $\sigma_p \gg \sigma_n$ . We may conclude from (4) that

$$J_p(x = x_n) \gg J_n(x = -x_p)$$

since  $L_p$  and  $L_n$  are typically comparable.

Total current density:

$$J = J_p(x = x_n) + J_n(x = -x_p) \approx J_p(x = x_n)$$

The current across the p<sup>+</sup>n junction is largely made up of the hole diffusion current in the quasi-neutral n region. Conversely, for a n<sup>+</sup>p junction, the current is mainly made up of the electron diffusion current in the quasi-neutral p region.

**Q4** Consider two ideal p-n junction diodes A and B at 300 K with the same diode current of 15 mA.

- Calculate the forward bias voltages applied if the reverse saturation current  $I_s$  is (a) 5  $\mu$ A for diode A and (b) 8 pA for diode B.
- If the diodes are made of Si and GaAs, which one corresponds to diode A? Explain briefly.

**(0.2 V, 0.53 V)**

Diode current is given as:

$$I = I_s \left( \exp \frac{qV_F}{kT} - 1 \right) \Rightarrow V_F = \frac{kT}{q} \ln \left( 1 + \frac{I}{I_s} \right)$$

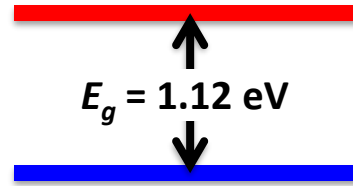
$$\text{For } I_s = 5 \mu\text{A}, V_F = 0.0259 \cdot \ln \left( 1 + \frac{15 \times 10^{-3}}{5 \times 10^{-6}} \right) = 0.2 \text{ V}$$

$$\text{For } I_s = 8 \text{ pA}, V_F = 0.0259 \cdot \ln \left( 1 + \frac{15 \times 10^{-3}}{8 \times 10^{-12}} \right) = 0.53 \text{ V}$$

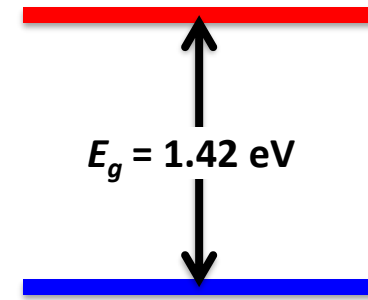
*Note:*  $V_F \downarrow$  as  $I_s \uparrow$  for the same current.

WHY? What's the physics?

$$V_{bi} = \frac{kT}{q} \ln \left( \frac{N_a N_d}{n_i^2} \right)$$

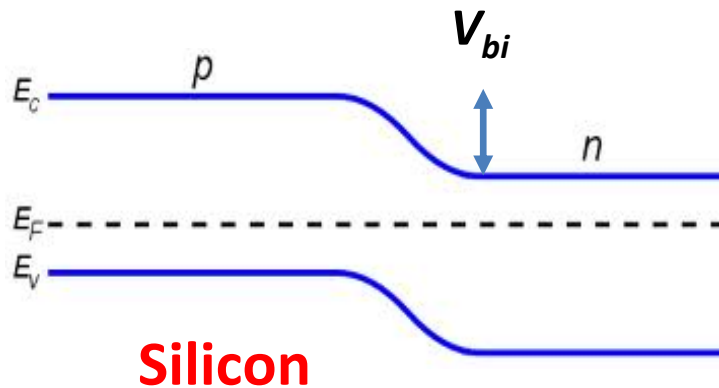


**Silicon**

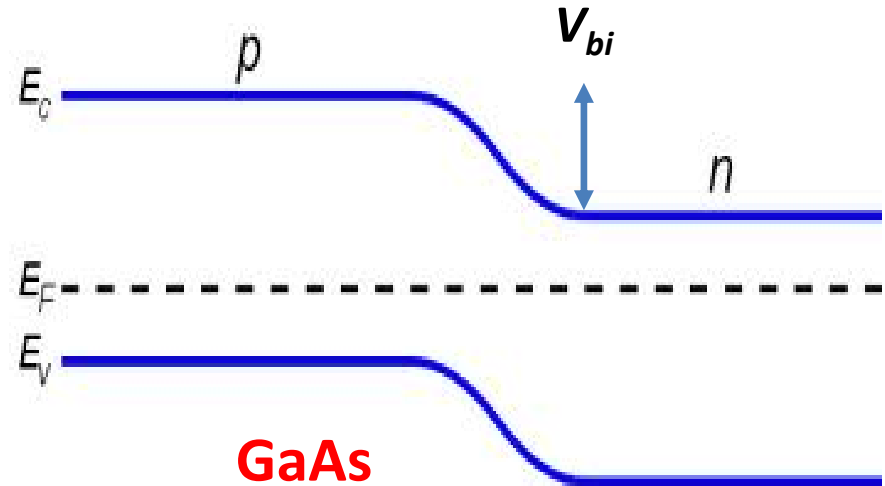


**GaAs**

- For higher band-gap materials, intrinsic carrier density is lower.
- $\therefore V_{bi}$  is higher, which is the potential barrier
- $\therefore$  more biasing voltage is required to achieve the same current as that in a lower band-gap material diode.

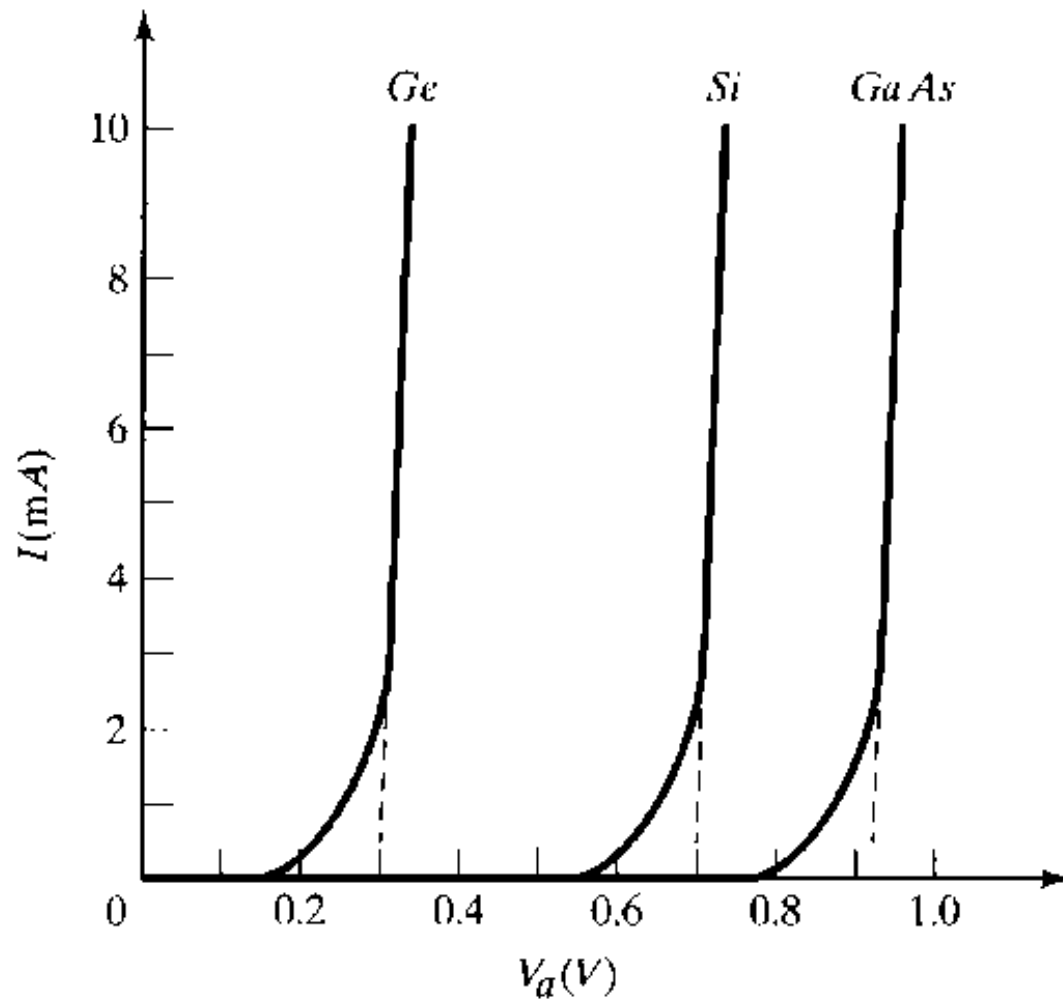


**Silicon**



**GaAs**

$V_{bi}$  of Si <  $V_{bi}$  of GaAs



$E_g$  of Ge  $<$   $E_g$  of Si  $<$   $E_g$  of GaAs

$V_{bi}$  of Ge  $<$   $V_{bi}$  of Si  $<$   $V_{bi}$  of GaAs